



PATENT APPLICATION
Serial No. 10/043,709

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CERTIFICATE OF MAILING (37 C.F.R. § 1.8)

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Signed:
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Kathy DKon

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re : Kuo-Yu Chou, et al. : Docket No. 67,200-603

Serial No. : 10/043,709 : Art Unit No. 2814

Filing Date : January 9, 2002 : Examiner: Le, Thao X

01/02/2003 Invention Title 10000005 10043709
01 FC:1202 72.00 OP A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM
AL FILM THICKNESS IN CU/FSG PROCESS FOR DEVICES
UNDER PADS

AMENDMENT AND RESPONSE TO OFFICE ACTION

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

November 25, 2002

Sir:

In response to the Official Action dated September 4, 2002, Applicants respectfully request reconsideration and further examination of all claims presented and entry of the following Amendment into the above-captioned patent application. Each of the amendments finds full support in the claims, specification, or drawings as filed. Therefore, please amend the above-captioned patent application, without prejudice, as follows: